



## Material Content Data Sheet



<b>Sales Product Name</b>				SAK-TC233LP-32F200N AC		<b>Issued</b>		31. July 2018	
<b>MA#</b>				MA001654632					
<b>Package</b>				PG-TQFP-100-23		<b>Weight*</b>		698.65 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	23.351	3.34	3.34	33423	33423	
leadframe	inorganic material	phosphorus	7723-14-0	0.056	0.01		80		
	non noble metal	zinc	7440-66-6	0.223	0.03		319		
	non noble metal	iron	7439-89-6	4.458	0.64		6381		
wires	non noble metal	copper	7440-50-8	181.029	25.91	26.59	259112	265892	
	noble metal	gold	7440-57-5	0.002	0.00		2		
	noble metal	palladium	7440-05-3	0.033	0.00		47		
encapsulation	non noble metal	copper	7440-50-8	1.466	0.21	0.21	2098	2147	
	organic material	carbon black	1333-86-4	1.408	0.20		2015		
	plastics	epoxy resin	-	59.588	8.53		85290		
leadfinish	inorganic material	silicondioxide	60676-86-0	408.203	58.45	67.18	584270	671575	
	noble metal	palladium	7440-05-3	0.003	0.00		4		
	noble metal	silver	7440-22-4	0.003	0.00		4		
plating	noble metal	gold	7440-57-5	0.005	0.00		7		
	non noble metal	nickel	7440-02-0	4.642	0.66	0.66	6645	6660	
	noble metal	silver	7440-22-4	0.005	0.00		7		
glue	noble metal	palladium	7440-05-3	0.005	0.00		8		
	noble metal	gold	7440-57-5	0.009	0.00		12		
	non noble metal	nickel	7440-02-0	8.662	1.24	1.24	12399	12426	
*deviation	plastics	epoxy resin	-	1.211	0.17		1733		
	noble metal	silver	7440-22-4	4.292	0.61	0.78	6144	7877	
						Sum in total:	100.00	1000000	

### Important Remarks:

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